

# MLA 150

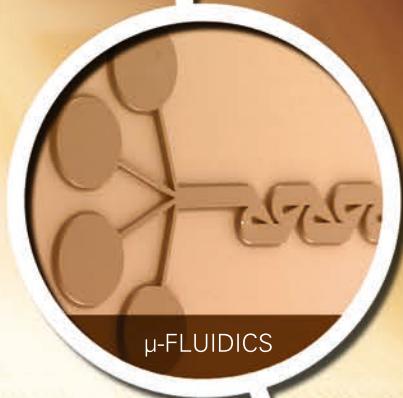
**HEIDELBERG**  
INSTRUMENTS



MEMS



DOE



μ-FLUIDICS



SENSORS

**MLA**  
MASKLESS ALIGNER



GO MASKLESS  
ACHIEVE MORE

**MLA 150**

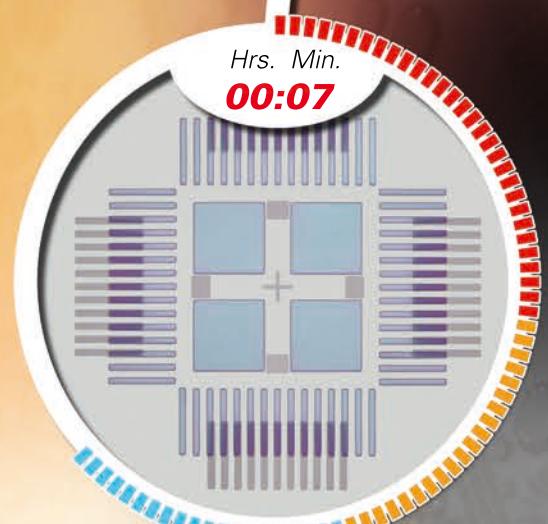
MORE INFO? SCAN THIS!

Hrs. Min.  
**00:03****STEP 1: SYSTEM SETUP**

- Intuitive User Interface
- Multi-user capabilities
- Support for all standard input formats (dxf, gdsii, cif, gerber)
- CAD Software for design creation included
- Resist database

Hrs. Min.  
**00:05****STEP 2: LOADING**

- Simple loading procedure
- One chuck for all substrates from 5 x 5 mm<sup>2</sup> to 150 x 150 mm<sup>2</sup>
- Automatic substrate size detection
- No need for edge-bead removal or wedge compensation

Hrs. Min.  
**00:07****STEP 3: ALIGNMENT**

- High precision topside and backside alignment
- Fast alignment procedure
- Distortion compensation
- Simple alignment on thick resists and small substrates
- Alignment accuracy ≤ 500 nm

Hrs. Min.  
**00:11****STEP 4: EXPOSURE**

- Min. feature size of 1µm
- Exposure time for 50 x 50 mm<sup>2</sup> approx. 4 min.
- Non-contact exposure
- High Aspect Ratio exposures in thick resist
- Automatic labeling and serialization
- Compatible to g-, h- and i-line resists

**GO MASKLESS** \_\_\_\_\_  
**ACHIEVE MORE**

Specifications depend on individual process conditions and can vary according to equipment configurations. Design and specifications are subject to change without prior notice.